

SEMICONDUCTOR DEVICE WITH STACK OF SEMICONDUCTOR CHIPS

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ABSTRACT OF THE DISCLOSURE

10 A semiconductor device is configured of a first
semiconductor chip mounted on a substrate, a plate member
arranged on the first semiconductor chip, and a second
semiconductor chip arranged on the plate member. Bonding
wires electrically connect the pads of the first
semiconductor chip and the pads of the second
15 semiconductor chip to the pads of the substrate, and a
sealing resin seals the first semiconductor chip and the
second semiconductor chip. A first portion of the plate
member is displaced away from the ends of the first and
second semiconductor chips, and a second portion of the
20 plate member extending perpendicular to the first
portion, projects outward from the first and second
semiconductor chips to be exposed to the outside.